

***Cold CMOS Electronics  
for the readout of  
very large LAr TPCs***

***Craig Thorn***

***On behalf of the LBNE LAr Working Group***

***TIPP 2011***

***June 11, 2011***

**Gianluigi De Geronimo, Alessio D'Anadragora\*, Shaorui Li, Neena Nambiar, Sergio Rescia, Emerson Vernon  
Hucheng Chen, Francesco Lanni, Don Makowiecki, Veljko Radeka, Craig Thorn, and Bo Yu**

***Brookhaven National Laboratory, NY, USA***

***\* University of L'Aquila, L'Aquila, Italy***

# Outline

- LAr40 overview
- The Cold Electronics System
- Analog Front End
- ADC
- Summary

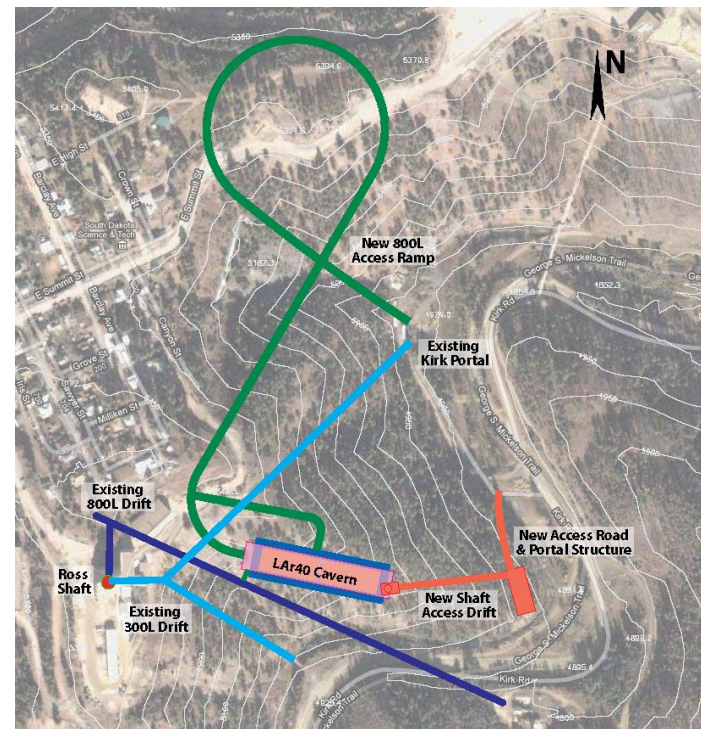
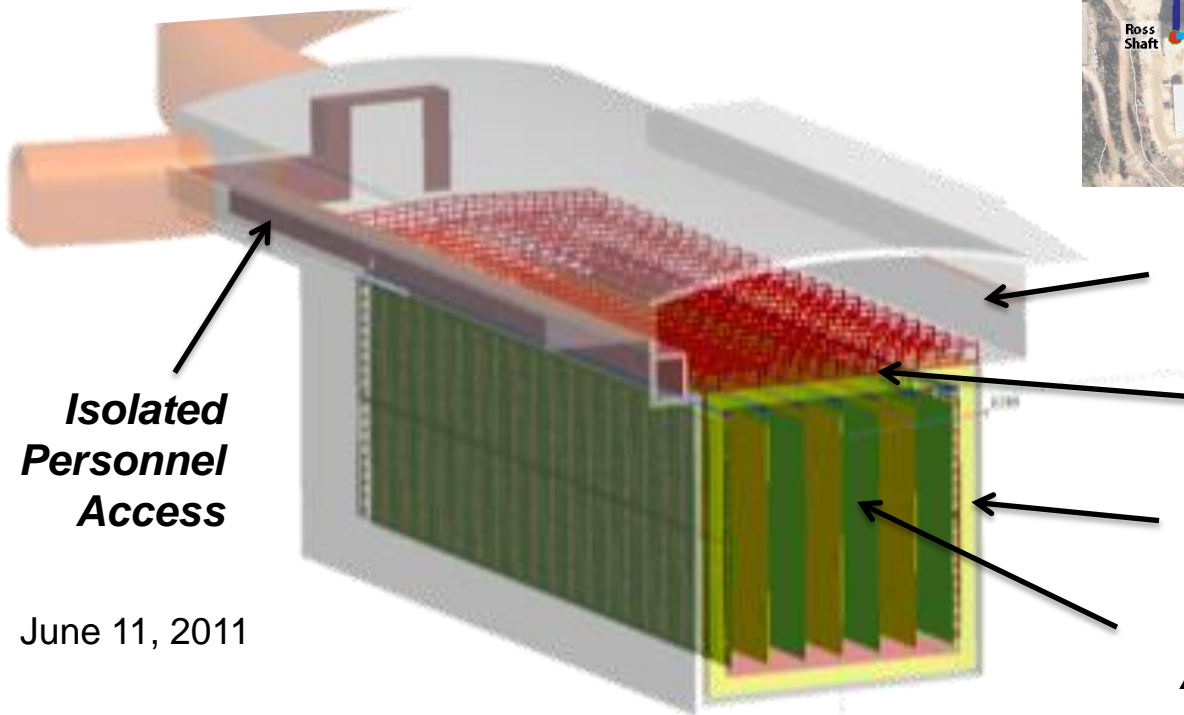
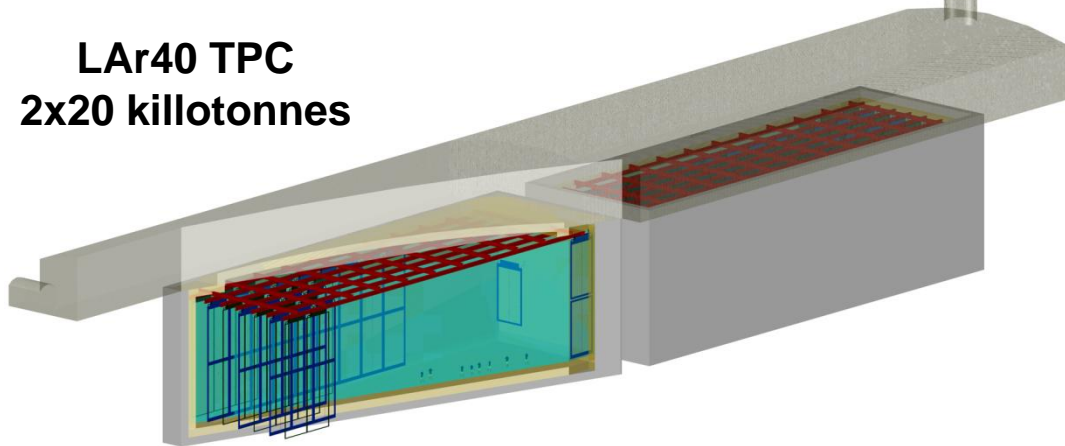
Other presentations at TIPP 2011 describing LBNE LAr40:

- *[412] Membrane cryostat technology and prototyping program towards kton scale Neutrino detectors, **Rucinski***
- *[422] Designs of Large Liquid Argon TPCs — from MicroBooNE to LBNE LAr40, **Yu***
- *[223] Front End Readout Electronics of the MicroBooNE Experiment, **Chen***

# LBNE LArTPC inside Cryostats in Cavern

Deep Underground Science & Engineering Lab (DUSEL) in Homestake, South Dakota, USA

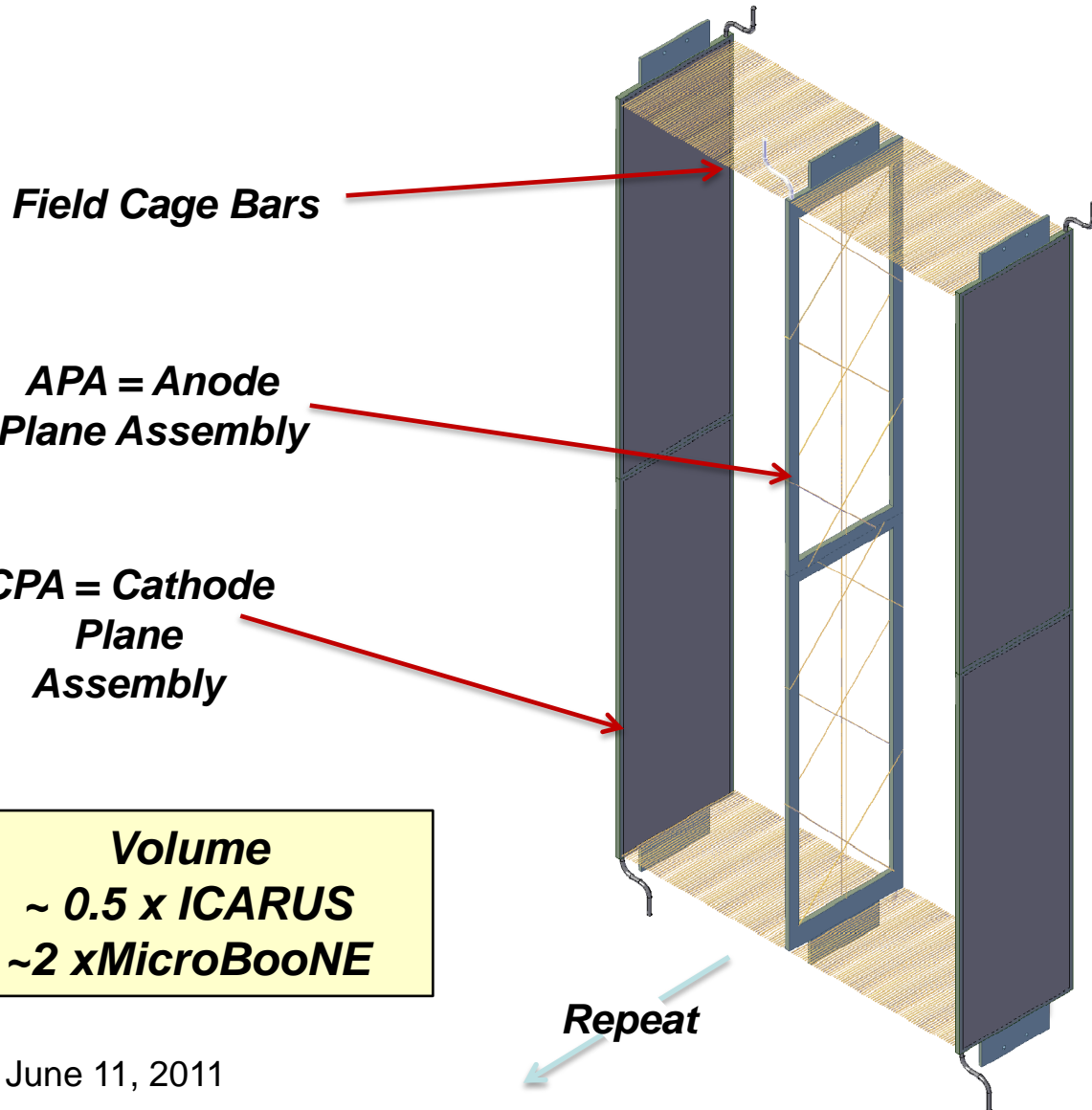
**LAr40 TPC**  
**2x20 kilotonnes**



**High Bay  
Access**  
**Truss Lid for  
Cryostat**  
**Membrane  
Cryostat**  
**TPC  
Arrays**

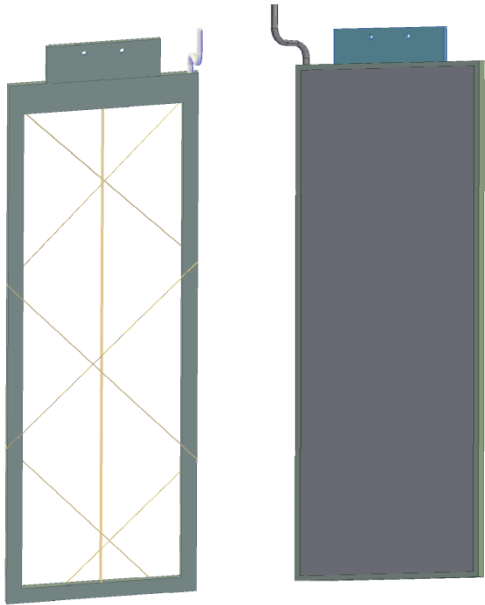
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# APA + CPA Assemblies form TPC modules in the Cryostat



**Unit Cell**  
**TPM = TPC Module**  
**= 1 APA + 1 CPA**  
**(+1 "terminal" CPA)**

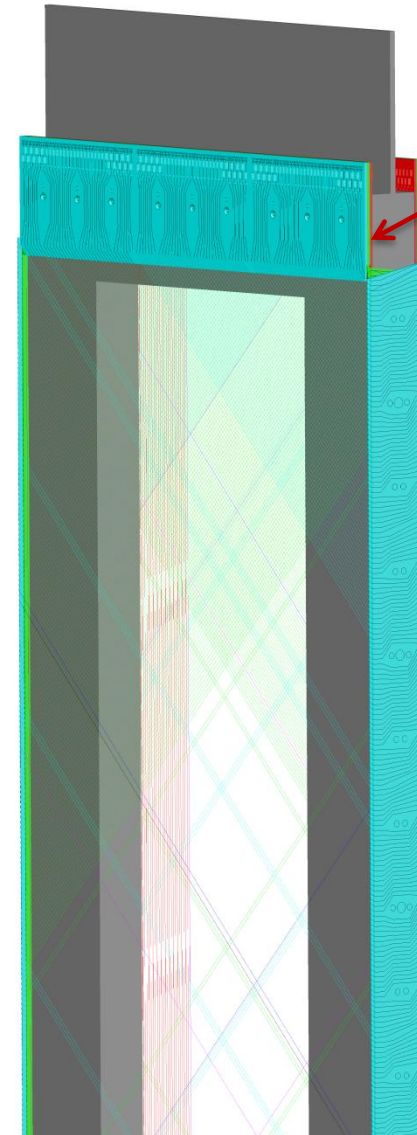
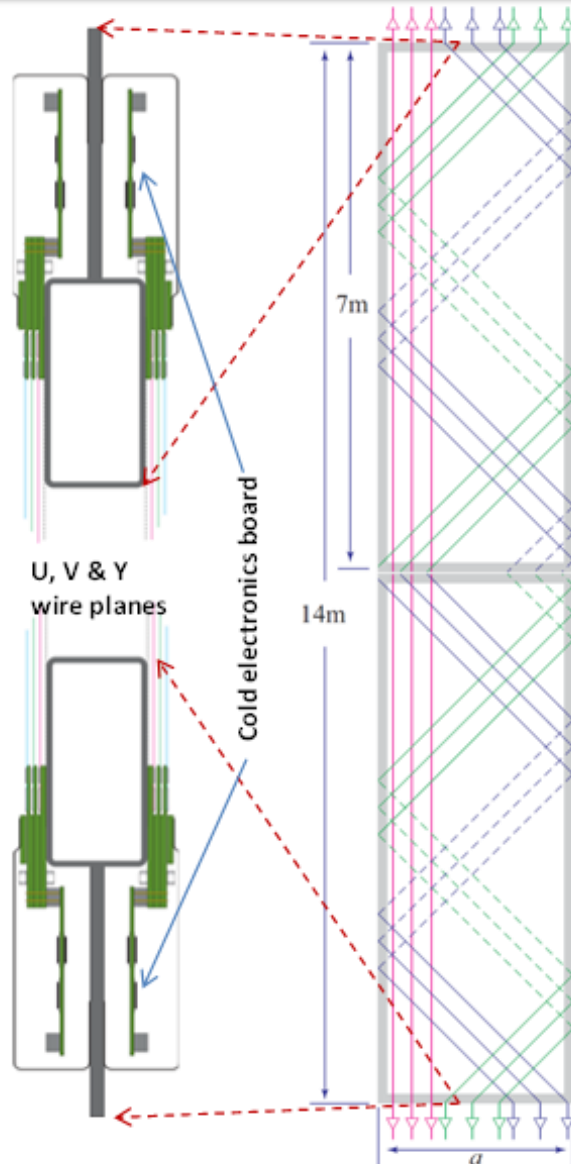
**Volume**  
**~ 0.5 x ICARUS**  
**~2 x MicroBooNE**



**APA**

**CPA**

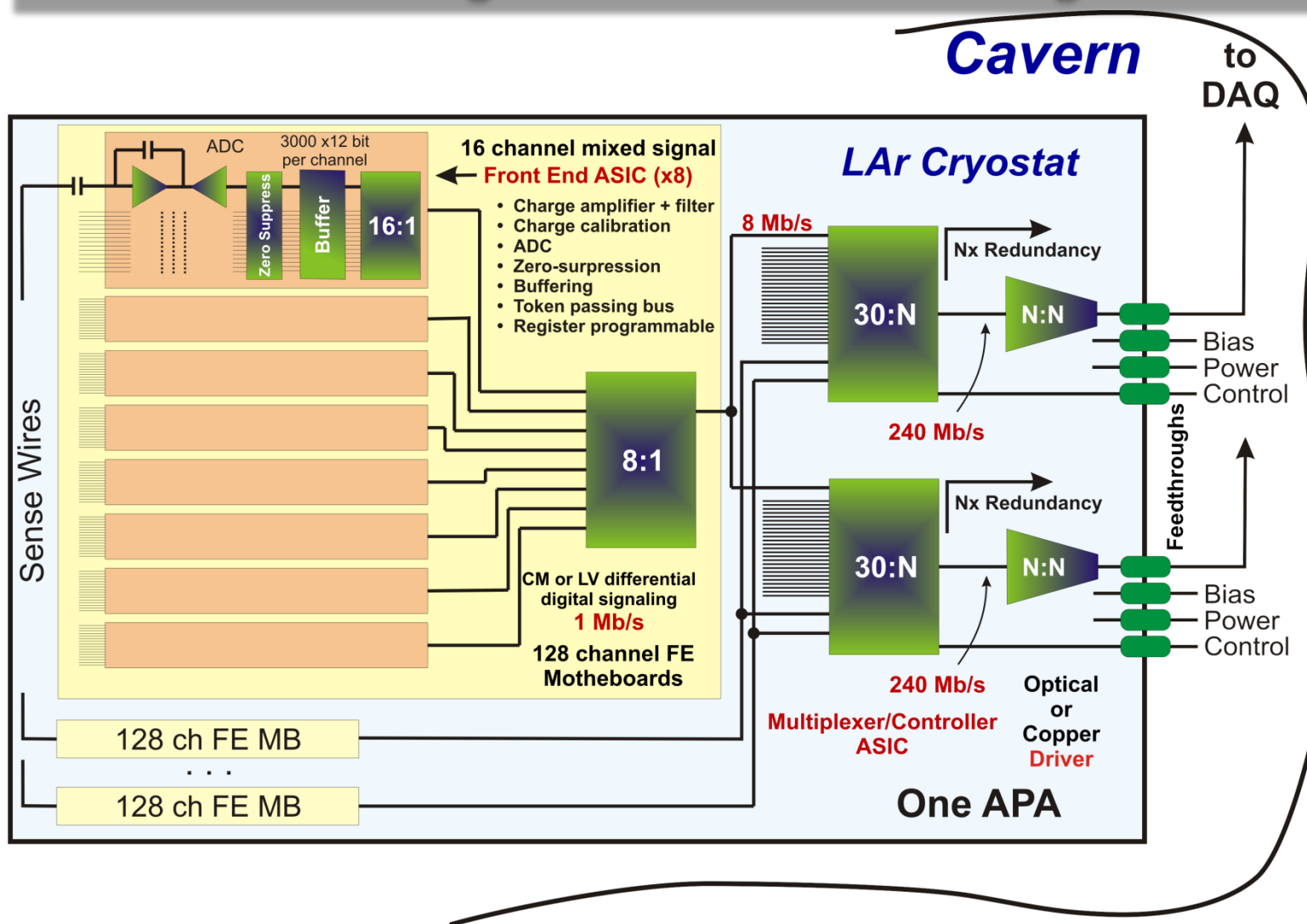
# Anode Plane Assembly (APA): the core element of a TPC unit



**Cold Electronics**

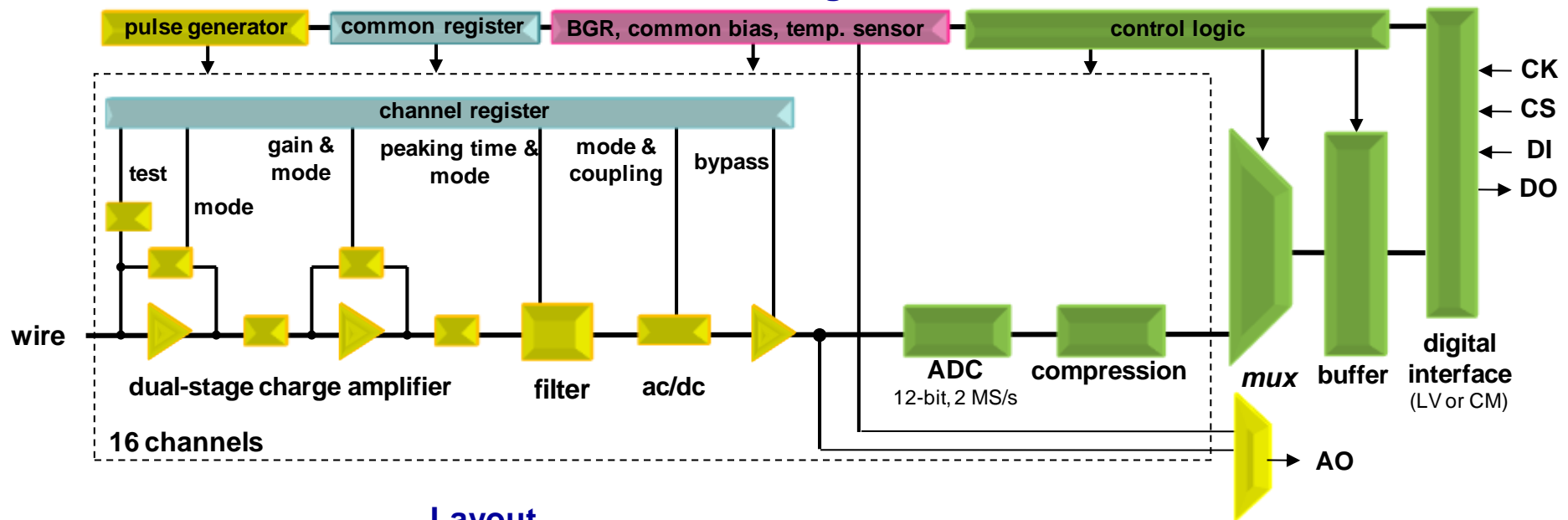
**APAs are structural and electrical units containing all sense wires and readout electronics. They can be tested in LN2 and stored and transported in shipping containers.**

# LAr TPC - Cold CMOS Electronics Block Diagram – Reference Design

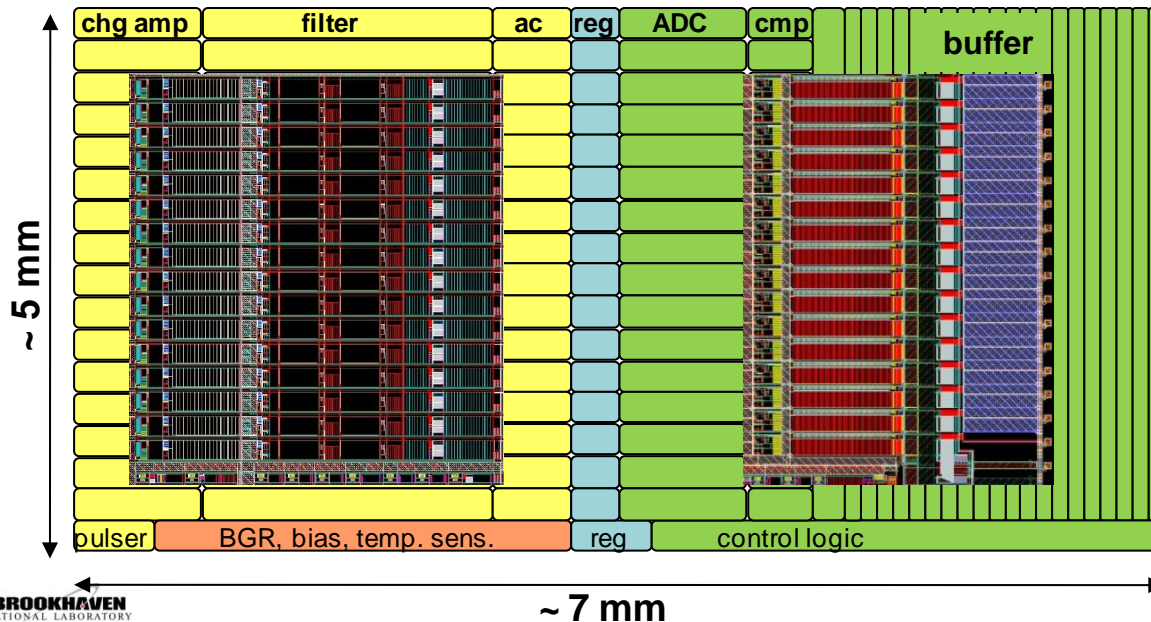


# LAr TPC Front-End ASIC

## Block Diagram



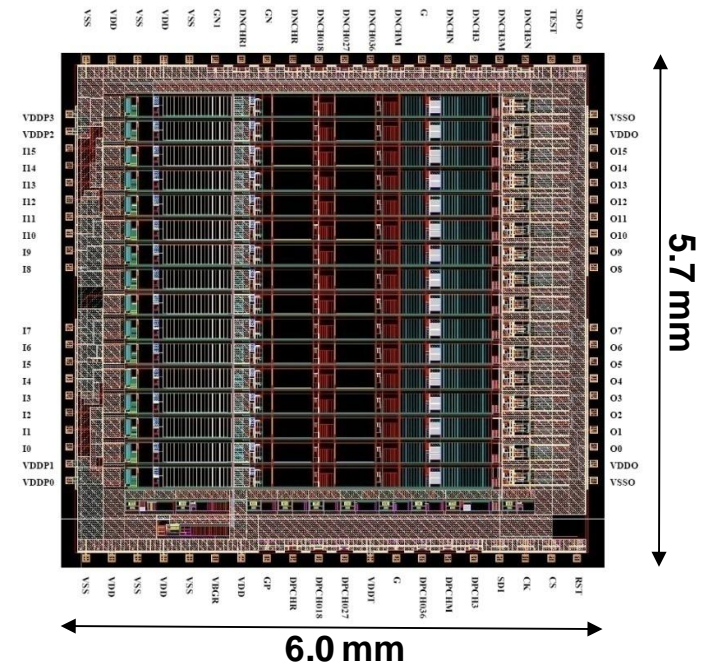
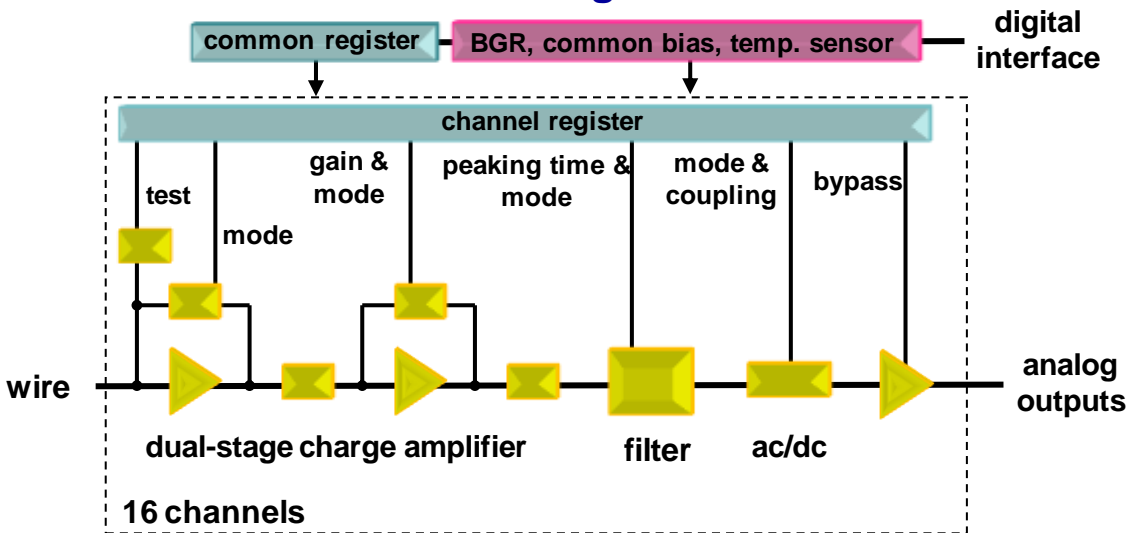
## Layout



- 16 channels
- charge amplifier (adj. gain)
- high-order filter (adj. time constant)
- ac/dc, adjustable baseline
- test capacitor. channel mask
- ADC (12-bit, 2 MS/s)
- compression, discrimination
- multiplexing and digital buffering
- LV or CM digital interface
- pulse generator, analog monitor
- temperature sensor
- LAr environment (> 20 years at 88K)
- estimated total size ~ 6 x 8 mm<sup>2</sup>
- estimated power ~ 10 mW/channel

# Analog ASIC

## Block Diagram

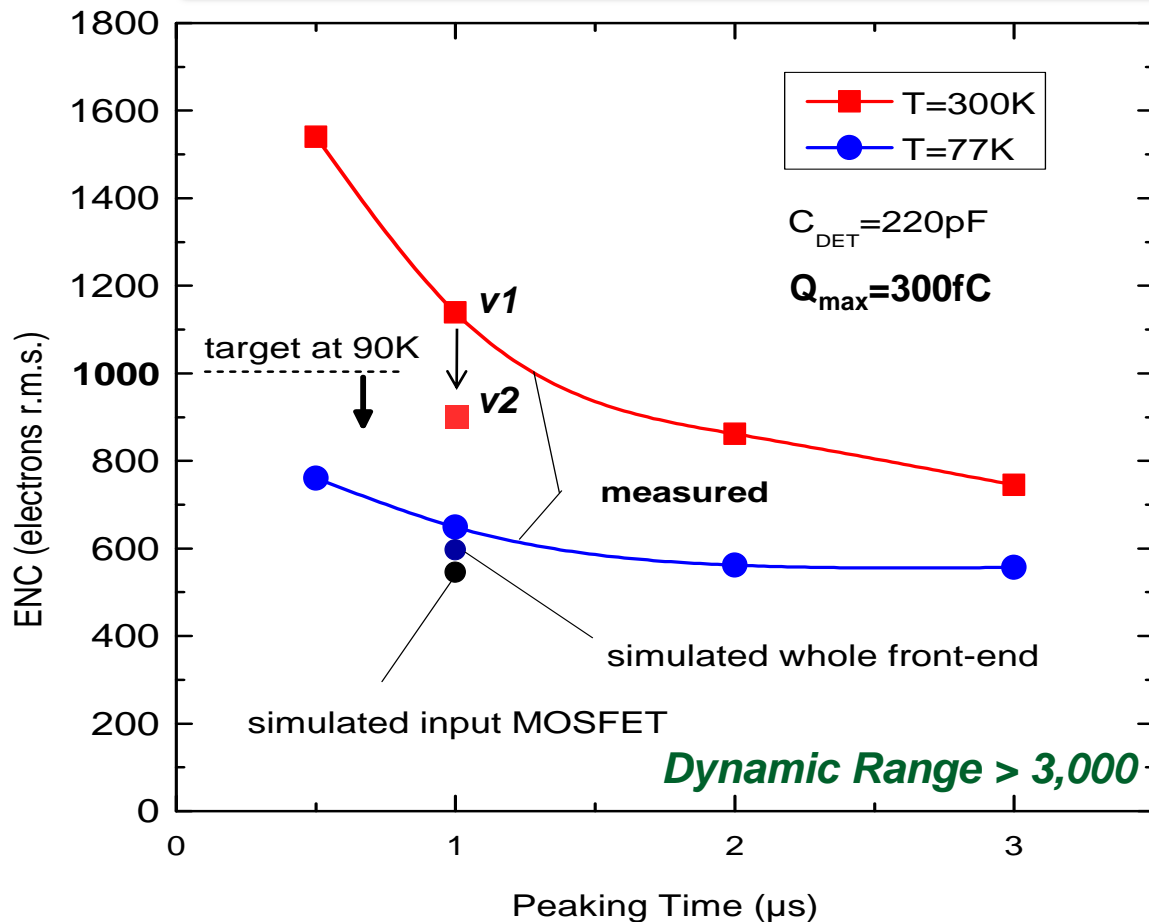


- 16 channels
- charge amplifier, high-order filter
- adjustable gain: 4.7, 7.8, 14, 25 mV/fC  
(charge 55, 100, 180, 300 fC)
- adjustable filter time constant  
(peaking time 0.5, 1, 2, 3  $\mu$ s)
- selectable collection/non-collection mode  
(baseline 200, 800 mV)
- selectable dc/ac coupling (100 $\mu$ s)

- rail-to-rail analog signal processing
- band-gap referenced biasing
- temperature sensor ( $\sim 3$ mV/ C)
- 136 registers with digital interface
- 5.5 mW/channel (input MOSFET 3.9 mW)
- single MOSFET test structures
- $\sim 15,000$  MOSFETs
- designed for room (300K) and cryogenic (77K) operation
- technology CMOS 0.18  $\mu$ m, 1.8 V



# Noise Measurements



## Layout Detail



### Input Line

$L \approx 1\text{ mm}$   
 $W = 3.5\ \mu\text{m}$   
 (M3 + M4)  
 $R_{77\text{K}} \approx 3\ \Omega$   
 $R_{300\text{K}} \approx 12\ \Omega$

### Input MOSFET

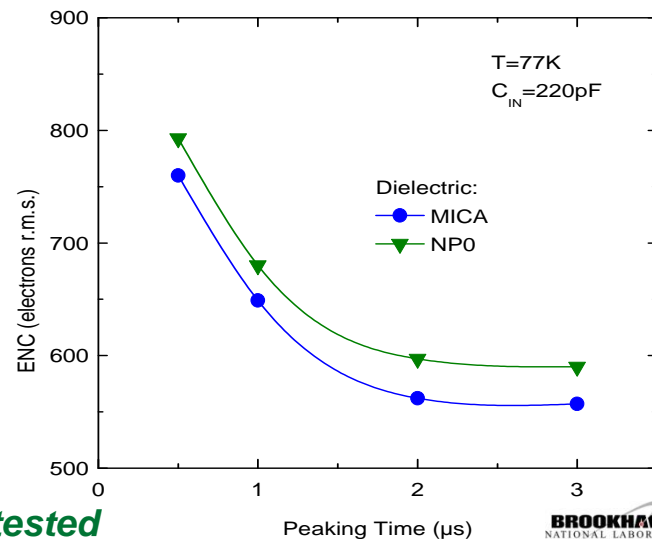
$L = 270\text{ nm}$   
 $W = 10\text{ mm}$   
 (50 $\mu\text{m} \times 200$ )  
 $g_{m,77\text{K}} \approx 90\text{ mS}$  (11  $\Omega$ )  
 $g_{m,300\text{K}} \approx 45\text{ mS}$  (22  $\Omega$ )

## Measurements affected by:

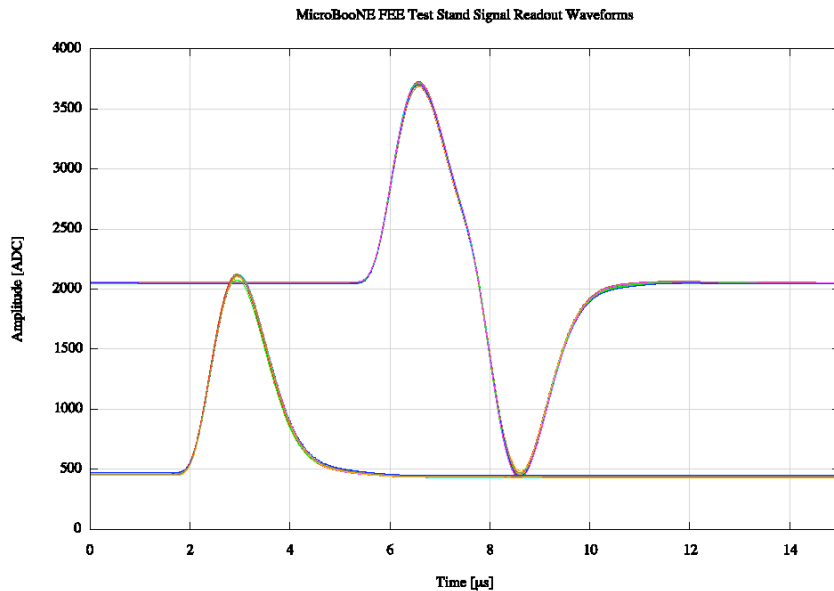
- input line **parasitic resistance**
  - ~ 150 e<sup>-</sup> at 77 K (~ 590 e<sup>-</sup> at 300K)
  - addressed in next revision
- $C_{\text{IN}}$  **dielectric noise (not present in wire)**
  - ~ 60 e<sup>-</sup> at 77 K

$$d\text{ENC} \approx \sqrt{2kTC_{\text{IN}}\text{tg}\delta}$$

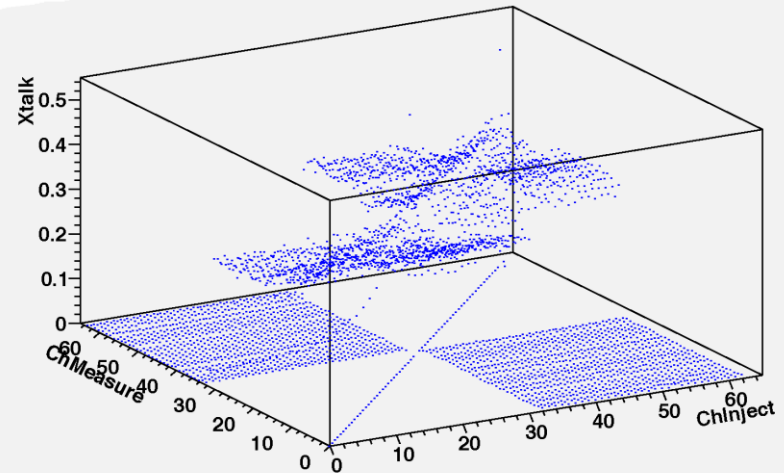
$$\approx \begin{cases} 200\text{ e}^- & \text{for NPO} \\ 60\text{ e}^- & \text{for MICA} \end{cases}$$



# FEE ASIC Evaluation



## Crosstalk Measurement



## FEE Test Stand for MicroBooNE is operational

- Full front end electronics chain, from CMOS ASIC to Receiver/ADC board, data is acquired to PC through FPGA board and Gigabit Ethernet
- One temporary 32 channel cold cable is available which has one broken channel
- Without detector capacitance, noise is  $\sim 200e^-$  with 1us peaking time
- Nonlinearity and crosstalk are less than 0.5%
- FEE test stand will be upgraded with the second version of ASICs and two prototype cold cables, more tests to follow

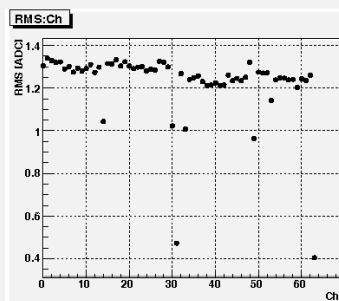
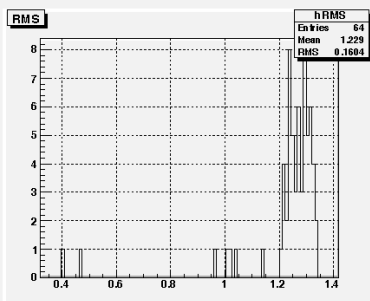
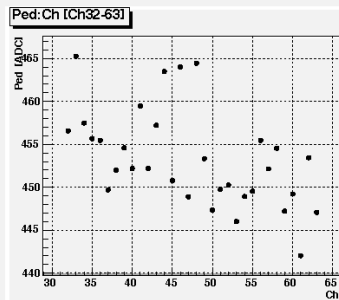
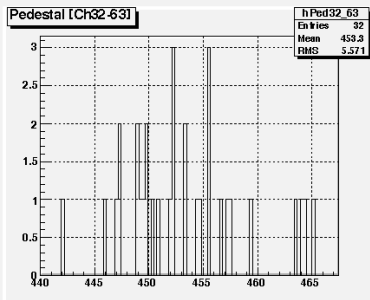
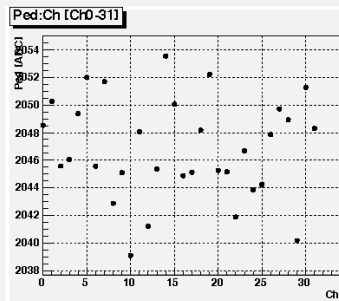
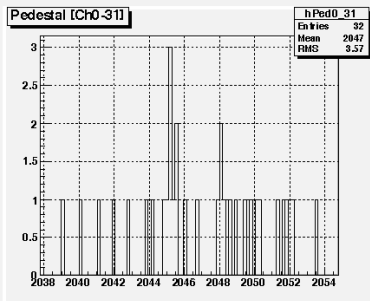
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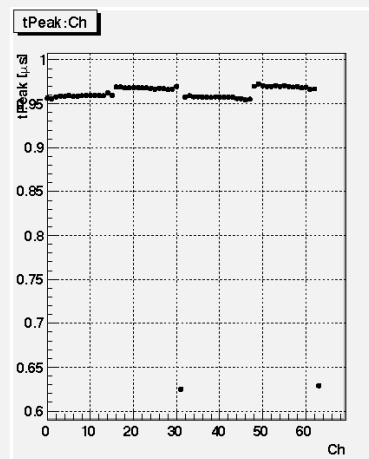
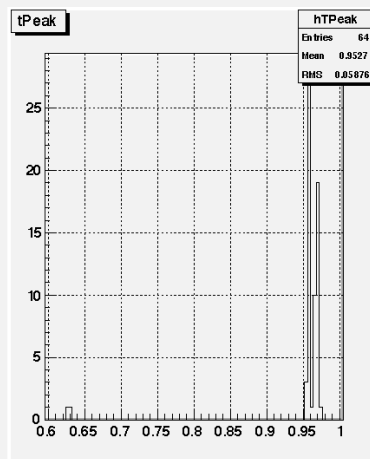
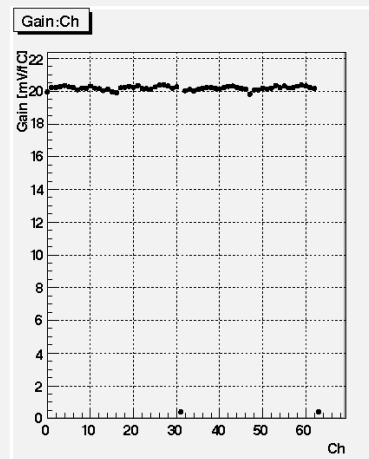
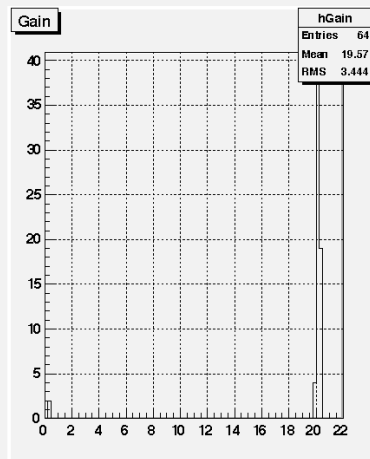


# FEE Analog ASIC Evaluation Noise, Gain & Shaping Time

## Noise Measurement

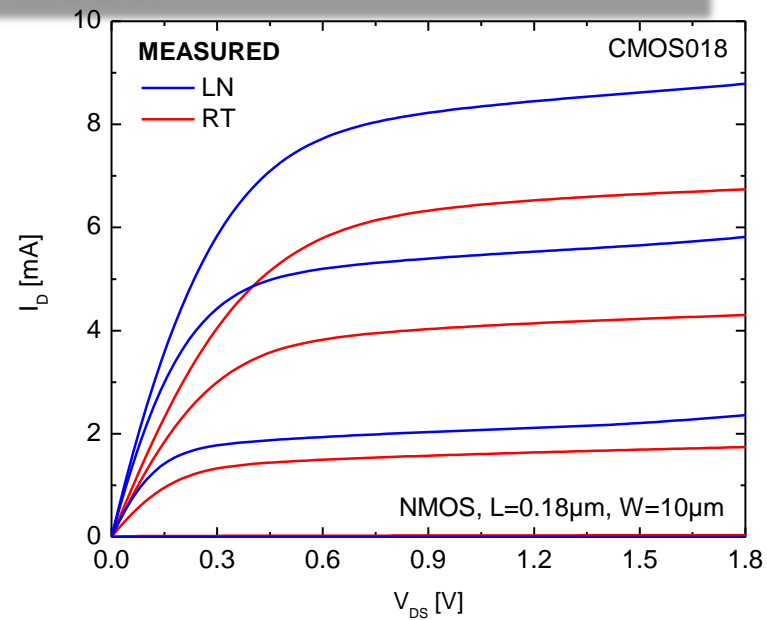
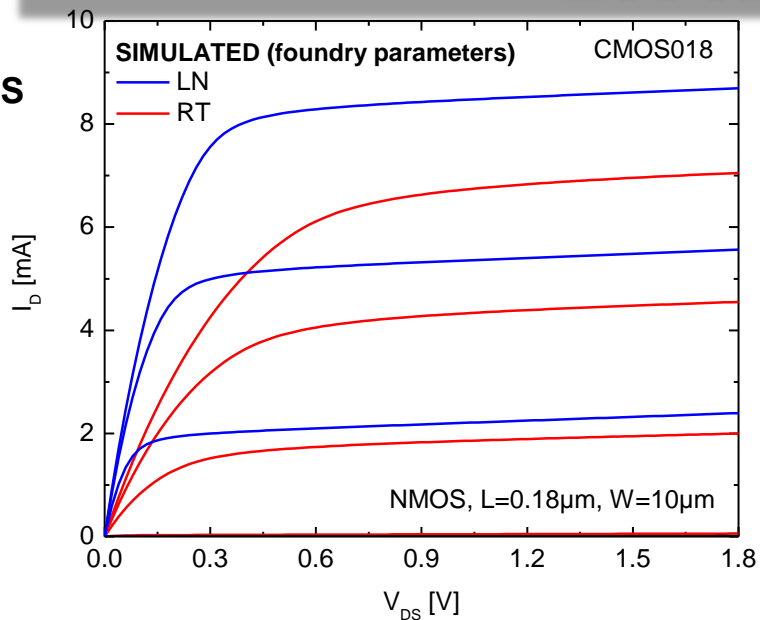


## Gain & Peaking Time Measurement

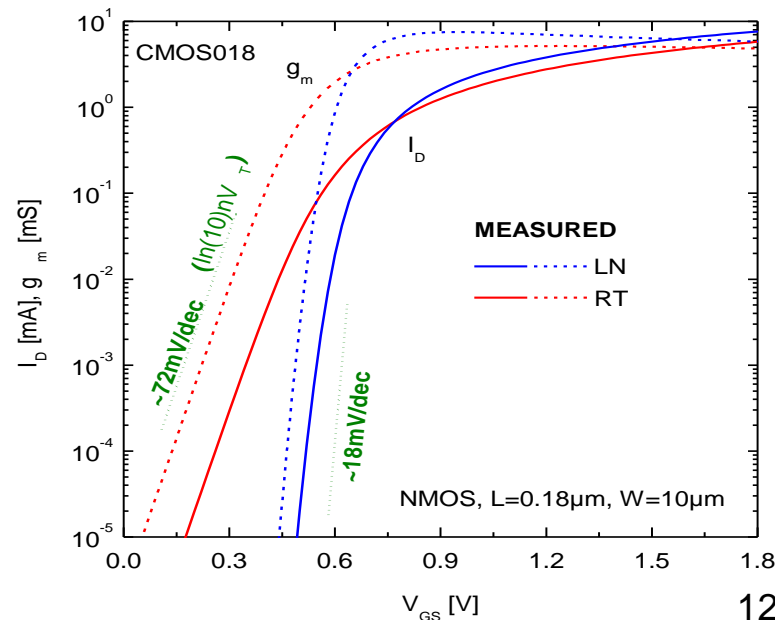
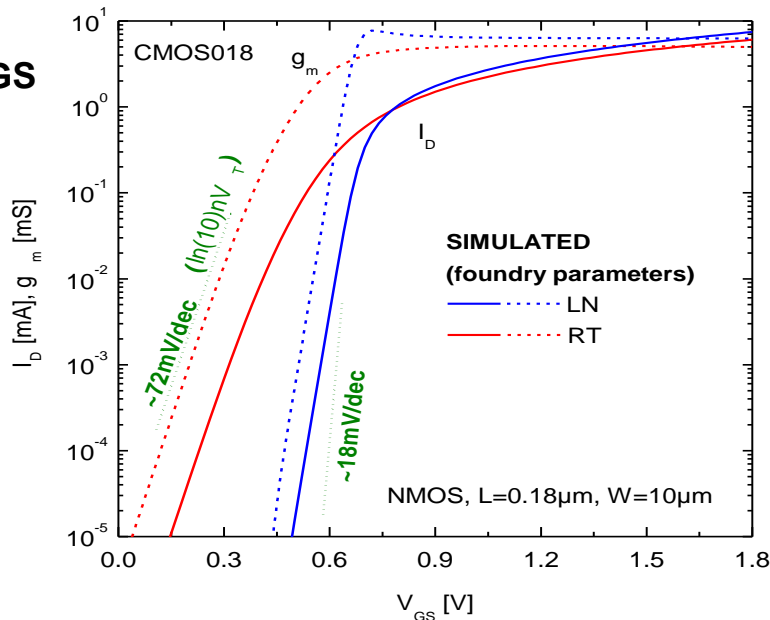


# MOS Static Model

$I_D$  vs  $V_{DS}$

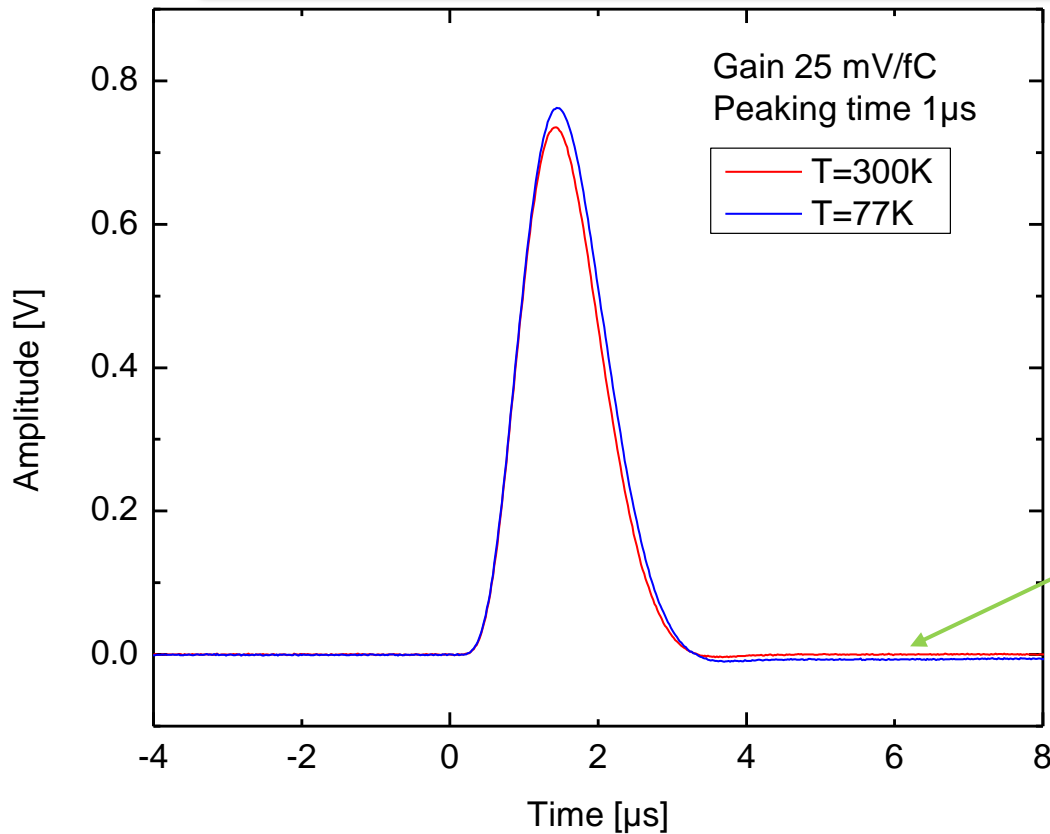


$I_D$  vs  $V_{GS}$



**Some differences in saturation voltage, sub-threshold slope, transconductance**

# Signal Measurements



## Bandgap Reference

$$V_{\text{BGR}} \approx \begin{cases} 1.185 \text{ V} & \text{at } 300 \text{ }^\circ\text{K} \\ 1.164 \text{ V} & \text{at } 77 \text{ }^\circ\text{K} \end{cases}$$

variation  $\approx 1.8 \%$

## Temperature Sensor

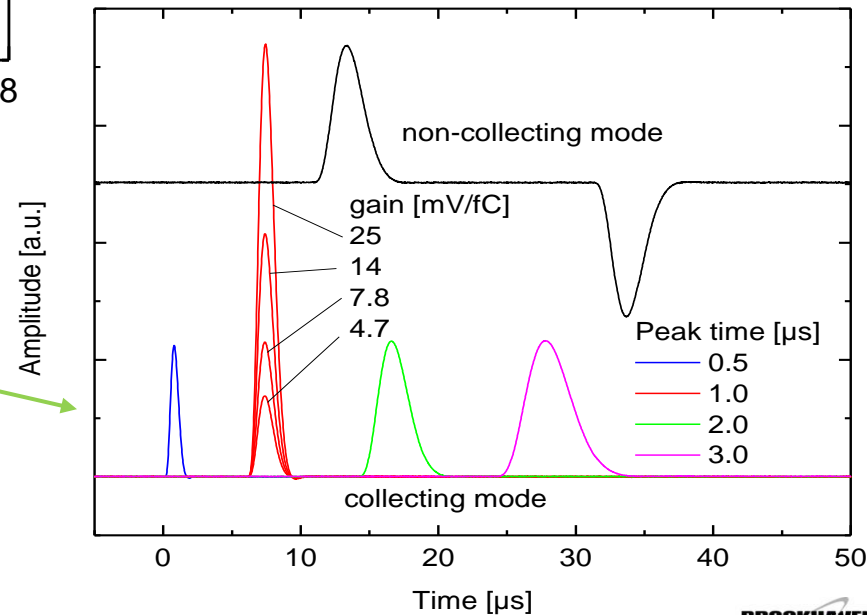
$$V_{\text{TMP}} \approx \begin{cases} 867.0 \text{ mV} & \text{at } 300 \text{ }^\circ\text{K} \\ 259.3 \text{ mV} & \text{at } 77 \text{ }^\circ\text{K} \end{cases}$$

$\sim 2.86 \text{ mV} / \text{K}$

**Pole-zero cancellation at 77K  
to be addressed in next revision**

Adjustable **gain**, peaking time and baseline

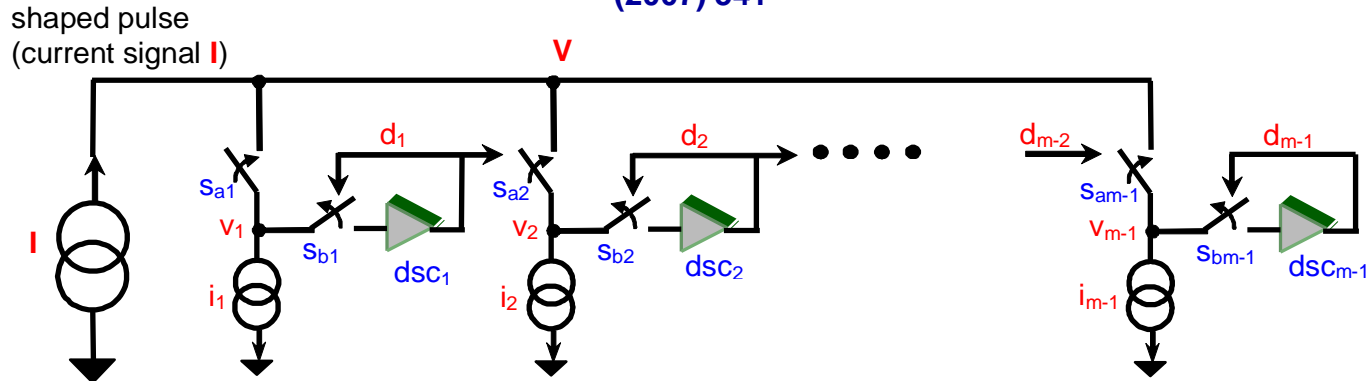
maximum charge 55, 100, 180, 300 fC



# ADC - Architecture

## Clockless low power ADC stage

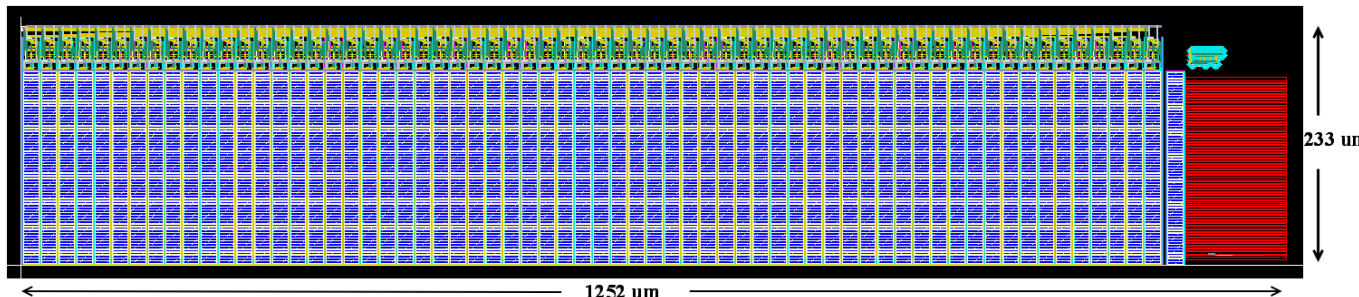
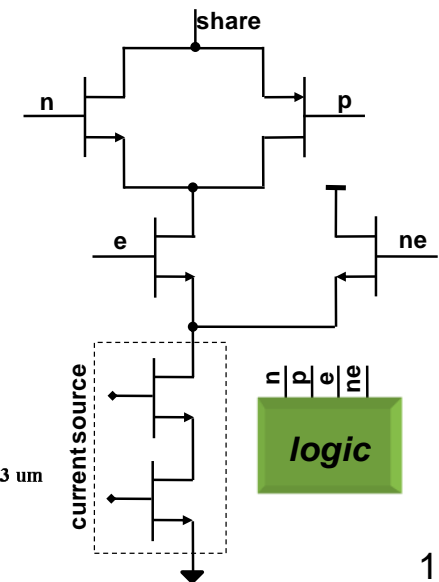
Demonstrated in ASIC for SNS, see De Geronimo, *et al.*, IEEE Trans NSS, 54 (2007) 541



### Current mode ADC

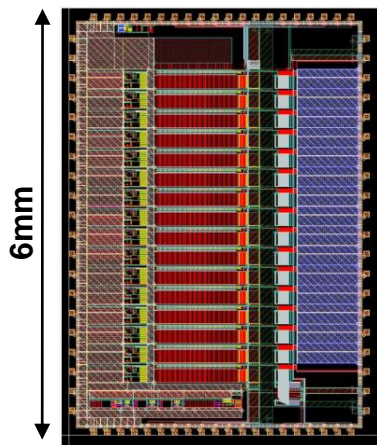
- **dual stage** 6-MSBs in 150ns, 6-LSBs in 250ns
- single trigger conversion per stage
- **12-bit resolution**
- **2 MS/s** conversion rate
- power dissipation **3.6 mW at 2 MS/s**
- **power-down** option for low rate applications
  - wake up in few tens of ns
- layout size: 0.23 mm x 1.25 mm

### ADC cell

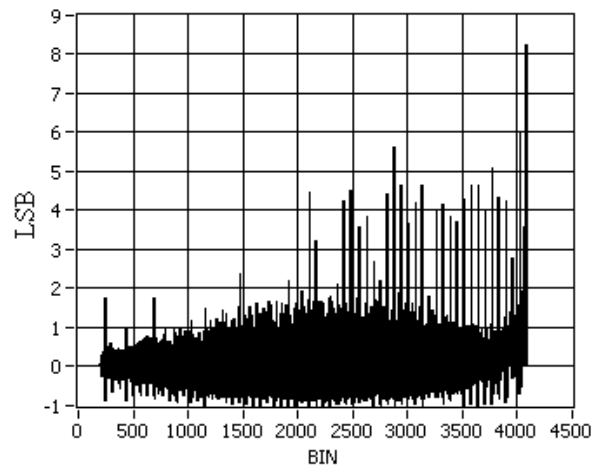


# ADC - Preliminary Results

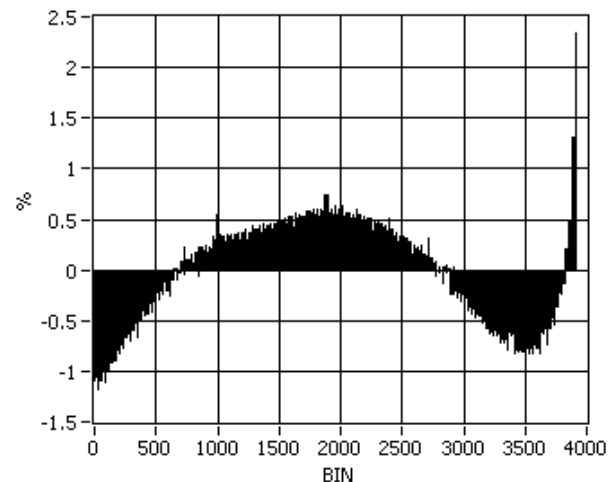
16-channel  
ADC+buffer



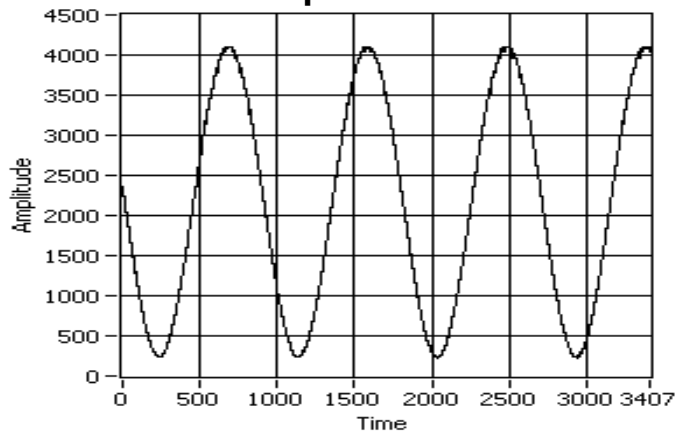
Differential Nonlinearity (DNL)



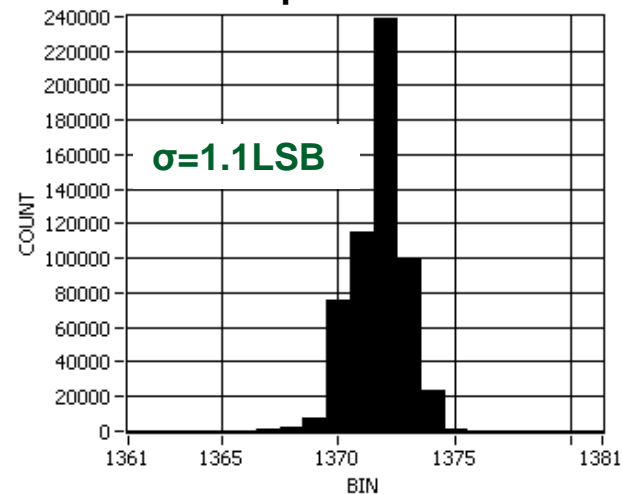
Integral Nonlinearity (INL) Percent



ADC output - 1.4 V sine



ADC output - 500mV dc



- operation verified at room and cryogenic temperatures
- differential non-linearity limited by timing design error in control circuit
- integral non-linearity limited by mismatch (linear  $\rightarrow$  common centroid)

ASIC revision being designed, to be fabricated in July

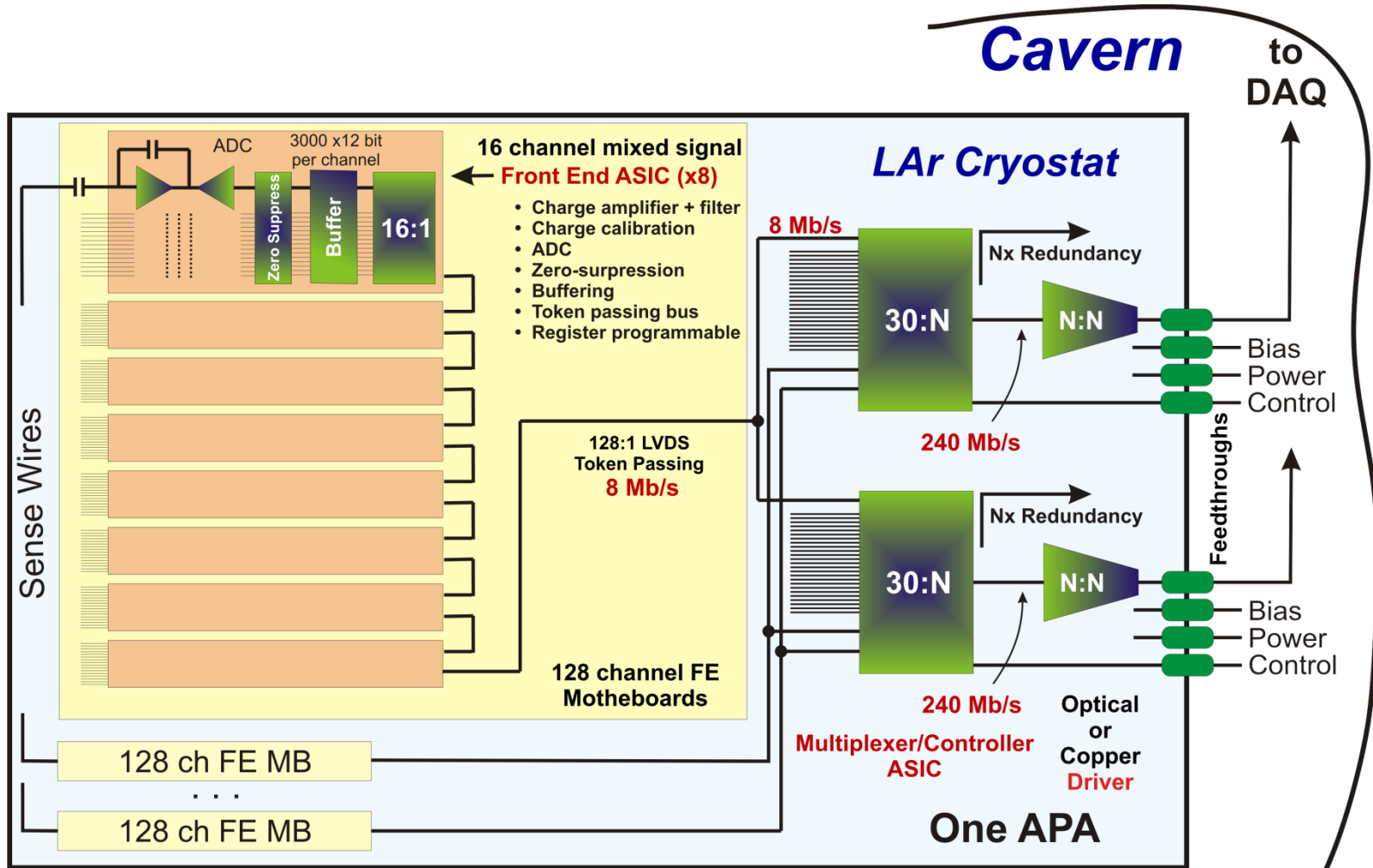
# Conclusions and Future Work

- **CMOS performs better** at cryogenic temperatures
- **Defined and predictable** design for cryogenic T is possible
- **Low-noise** at cryogenic T demonstrated
  - ENC < 1,000 e<sup>-</sup> at 200pF ~5mW/ch.
  - characterization and modeling of CMOS 180nm
- **Long lifetime** at cryogenic T possible with guidelines
- Critical **building blocks** - front-end & ADC - developed
- **Future work**
  - Improve cryogenic static models
  - Optimize ADC
  - Merge, add zero-suppression & buffering, and finalize

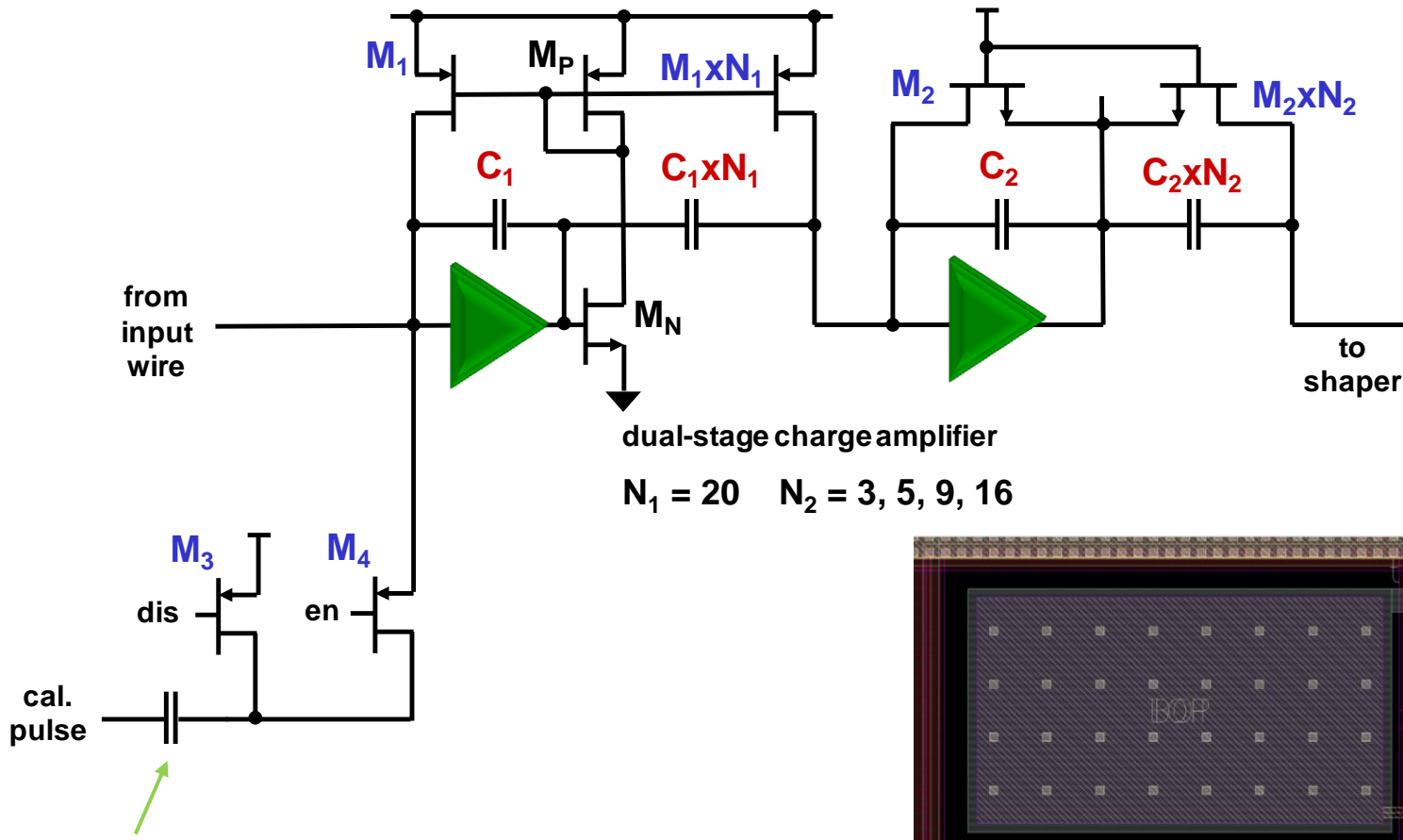


# Backup Slides

# LAr TPC - Cold CMOS Electronics Block Diagram – Alternate Design



# Calibration Scheme



$C_{INJ} = 180$  fF nominal

**Integrated** injection capacitance ( $10 \times 18 \mu\text{m}^2$ )

**Disabled** (grounded) when unused

**Measured** with high-precision external capacitance

$$C_{INJ} \approx \begin{cases} 184 \text{ fF} & \text{at } 300\text{K} \\ 183 \text{ fF} & \text{at } 77\text{K} \end{cases}$$

**change ~ 0.5%**

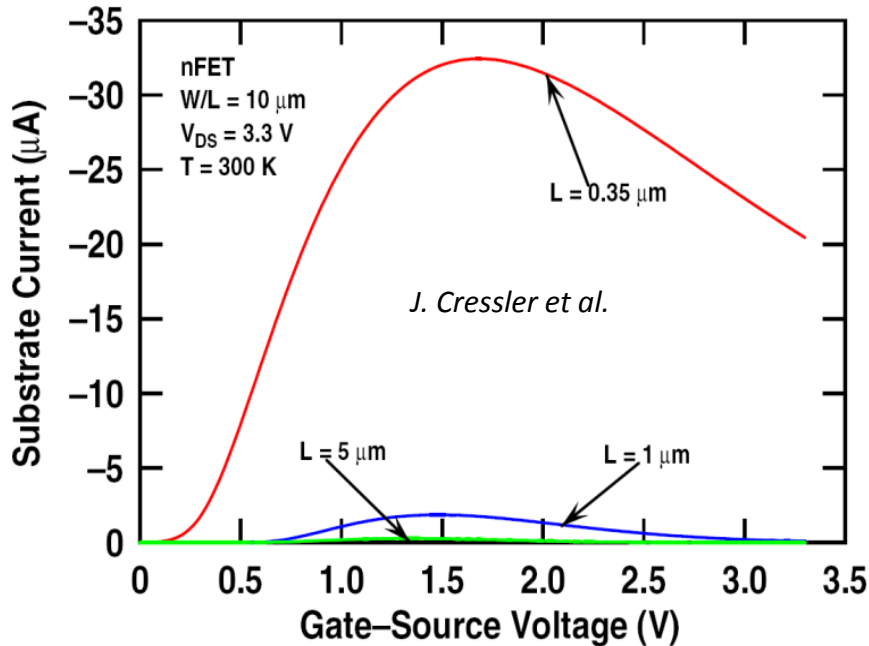
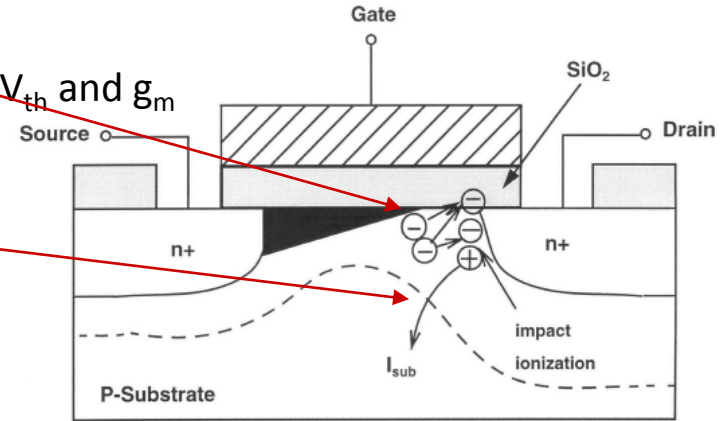
# Lifetime - Basic Mechanism

- **Degradation is due to impact ionization**

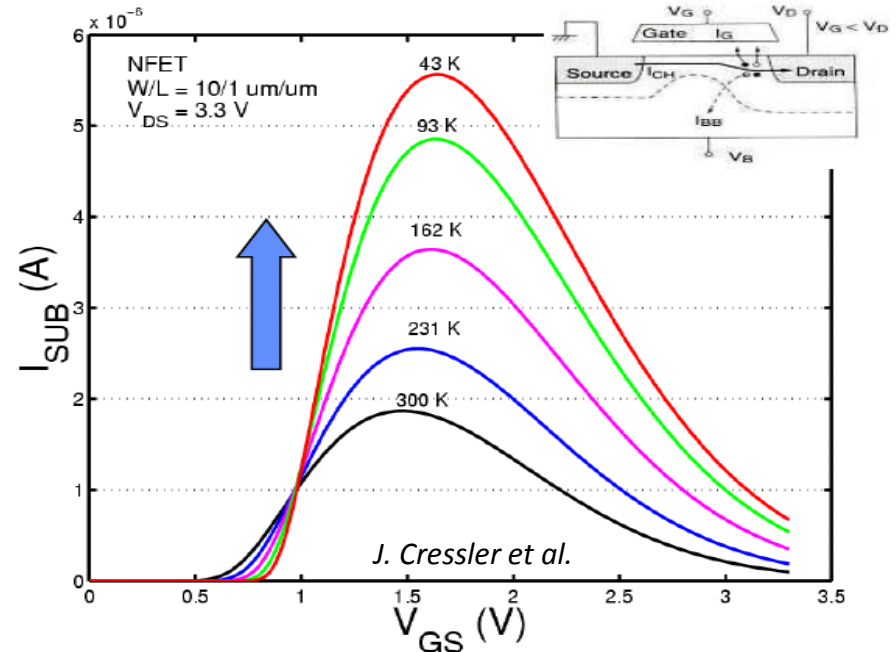
- charge trap in oxide, interface generation → shift in  $V_{th}$  and  $g_m$

- **Substrate current is a monitor of impact ionization**

- increases with **drain voltage**
- is higher in **short channel** devices
- has a **maximum** at  $V_{GS} \approx V_{DS}/2$



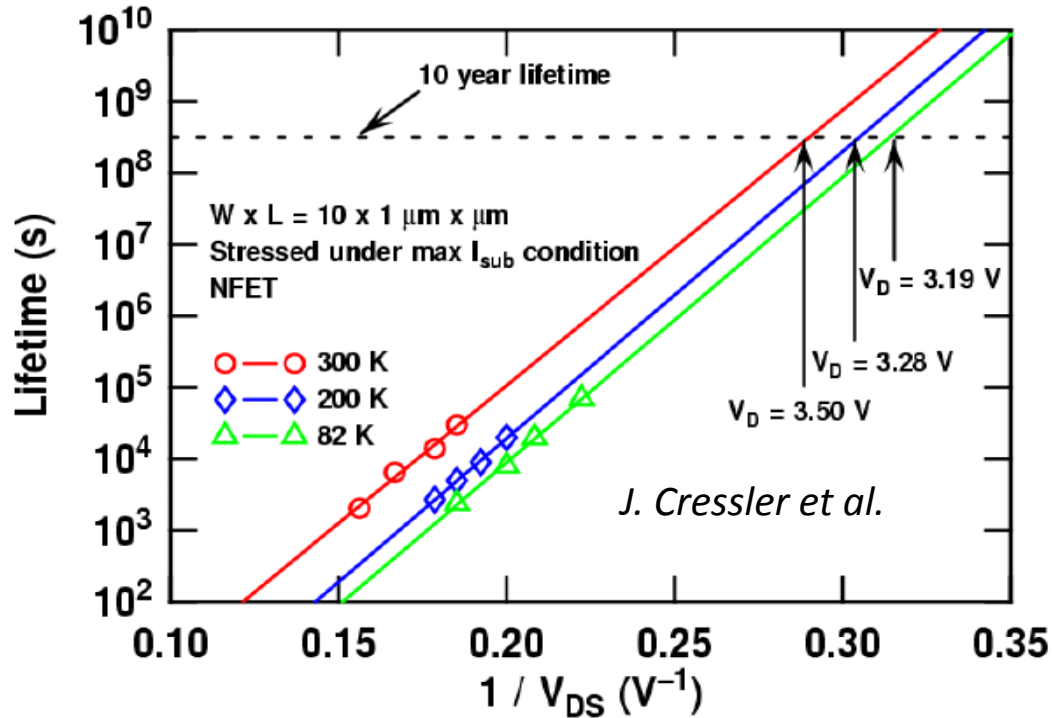
- **increases as the temperature decreases**



Commercial technologies are rated 10 years lifetime (10%  $g_m$  shift) in continuous ring oscillator operation:  $T = 300 \text{ K}$ ,  $L = L_{min}$ ,  $V_{ds} = \text{nominal } V_{DD} + 5\%$ ,  $V_{GS} \approx V_{DS}/2$

# Lifetime - Design Guidelines

Accelerated tests at increased  $V_{DS}$  allow extrapolation of lifetime



Desired lifetime at low temperature can be achieved by:

1. **decreasing  $V_{DS}$**  (e.g. decreasing the supply voltage)
2. **decreasing  $J_D$**  (i.e. decreasing the drain current density)
3. **increasing  $L$**  (i.e. non-minimum channel length devices)

Design guidelines can be obtained for:

analog circuits

- operate devices at **low current density**
- use **non-minimum channel length  $L$**

digital circuits

- operate devices at **-10% of nom.  $V_{DD}$**
- use **non-minimum channel length  $L$**
- operate at **low clock frequency**